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3510-DS-P

DEPARTMENT OF COMMERCE

Foreign-Trade Zones Board

[B-111-2026]

Foreign-Trade Zone (FTZ) 27, Notification of Proposed Production Activity; Rochester Electronics, LLC; (Semiconductor Products); Newburyport, Massachusetts

The Massachusetts Port Authority, grantee of FTZ 27, submitted a notification of proposed production activity to the FTZ Board (the Board) on behalf of Rochester Electronics, LLC for Rochester's facilities in Newburyport, Massachusetts within FTZ 27. The notification conforming to the requirements of the Board's regulations (15 CFR 400.22) was received on September 3, 2026.

Pursuant to 15 CFR 400.14(b), FTZ production activity would be limited to the specific foreign-status material(s)/component(s) and specific finished product(s) described in the submitted notification (summarized below) and subsequently authorized by the Board. The benefits that may stem from conducting production activity under FTZ procedures are explained in the background section of the Board's website – accessible via www.trade.gov/ftz.

The proposed finished products include: Light-emitting diodes (LEDs); Semiconductor microprocessors; and Semiconductor microcontrollers (duty free).

The proposed foreign-status materials/components include: Epoxy molding compound (epoxy cresol novolac resin) for plastic package encapsulation; Flexible plastic (PVC) tubes for component handling; Flexible plastic (PVC/polyethylene) pipes; Flexible plastic (PVC/polyethylene) hoses; Plastic boxes for packaging and shipment of finished semiconductor devices; Plastic cases for packaging and shipment of finished semiconductor devices; Plastic crates for packaging and shipment of finished

semiconductor devices; Gold bonding wire for semiconductor wire bonding; Bare printed circuit boards; unpackaged Semiconductor chips; Bare semiconductor die; Diffused monocrystalline silicon wafers bearing completed LED die, prior to singulation; Diffused monocrystalline silicon wafers, 100 mm (4-inch) to 200 mm (8-inch) diameter, bearing completed integrated circuit die, prior to singulation; Microprocessor integrated circuits used as inputs; Microcontroller integrated circuits used as inputs; Amplifier integrated circuits; Analog-to-digital converter integrated circuits; Lead frames for integrated circuits, copper alloy, supplied in strip form; and Lead frames for LEDs, copper alloy, supplied in strip form (duty rate ranges from duty-free to 6.1%).

The request indicates that certain materials/components are subject to duties under section 301 of the Trade Act of 1974 (section 301), depending on the country of origin. The applicable section 301 decision requires subject merchandise to be admitted to FTZs in privileged foreign status as described in 19 CFR 146.41.

Public comment is invited from interested parties. Submissions shall be addressed to the Board's Executive Secretary and sent to: ftz@trade.gov. The closing period for their receipt is **[INSERT DATE 40 DAYS AFTER DATE OF PUBLICATION IN THE FEDERAL REGISTER]**.

A copy of the notification will be available for public inspection in the "Online FTZ Information System" section of the Board's website.

For further information, contact John Frye at John.Frye@trade.gov.

Dated: September 18, 2026.

Colin Agostisi,
Executive Secretary.

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